

IN THE CLAIMS:

Please cancel Claims 4 and 5 and amend Claims 1 and 10 as follows:

*a2*

1. (Amended) An ultrasonic transducer, comprising:  
an ultrasonic sensor having a plurality of elements; and  
an integrated circuit formed on a wafer, the wafer including a plurality of cavities defining a plurality of posts such that the cavities alter the acoustic impedance of the wafer, and wherein the integrated circuit is joined to the ultrasonic sensor and wherein each of the elements of the ultrasonic sensor is located over one of a respective one of the plurality of posts and a respective one of the plurality of cavities.

*a3*

10. (Amended) The transducer of claim 1, wherein the cavities are configured and dimensioned for altering the acoustic impedance of the wafer to increase the effective bandwidth of the transducer elements.